



Material Content Data Sheet



Sales Product Name		IDD09E60		Issued		20. July 2018		
MA#		MA000043931						
Package		PG-TO252-3-11		Weight*		363.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.789	0.22	0.22	2171	2171
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		592	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		178	
	non noble metal	copper	7440-50-8	215.017	59.12	59.20	591302	592072
wire	non noble metal	aluminium	7429-90-5	0.556	0.15	0.15	1529	1529
encapsulation	organic material	carbon black	1333-86-4	1.231	0.34		3384	
	inorganic material	antimonytrioxide	1309-64-4	2.461	0.68		6768	
	plastics	brominated resin	-	2.461	0.68		6768	
	plastics	epoxy resin	-	24.610	6.77		67679	
	inorganic material	silicondioxide	60676-86-0	92.289	25.38	33.85	253798	338397
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10285	10285
plating	non noble metal	nickel	7440-02-0	0.091	0.02		250	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	251
solder	noble metal	silver	7440-22-4	0.023	0.01		62	
	non noble metal	tin	7440-31-5	0.018	0.00		50	
	non noble metal	lead	7439-92-1	0.864	0.24	0.25	2375	2487
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		53	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52739	52808
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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